

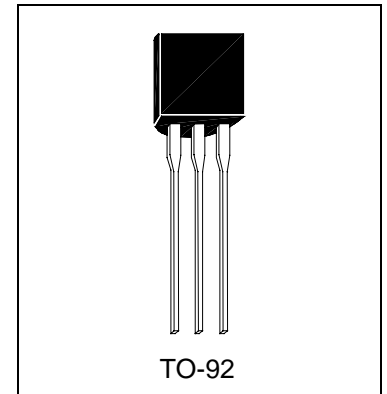


# H2N3906

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The H2N3906 is designed for general purpose switching and amplifier applications.



## Absolute Maximum Ratings

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
  - VCBO Collector to Base Voltage ..... -40 V
  - VCEO Collector to Emitter Voltage..... -40 V
  - VEBO Emitter to Base Voltage..... -5 V
  - IC Collector Current ..... -200 mA

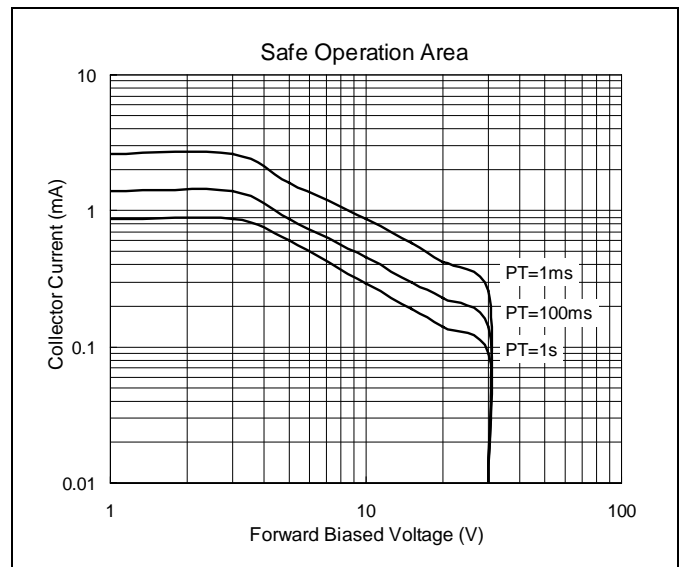
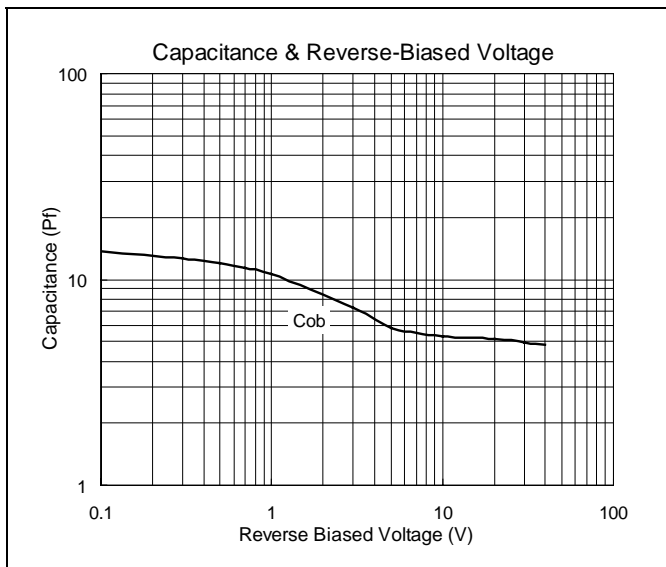
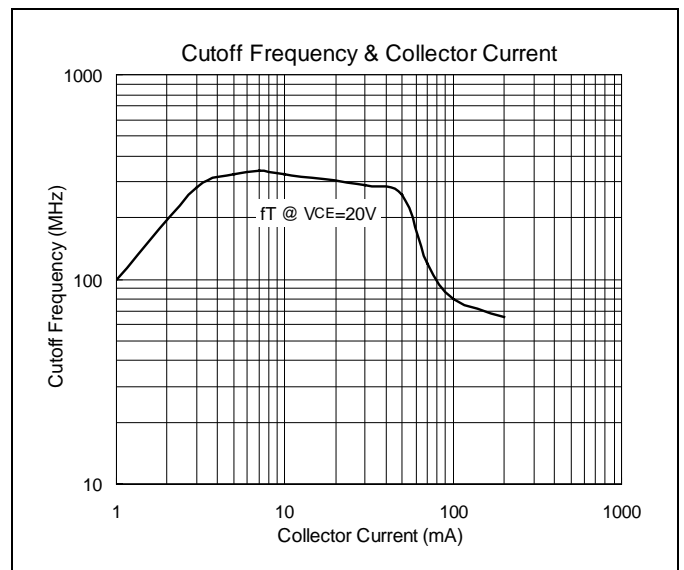
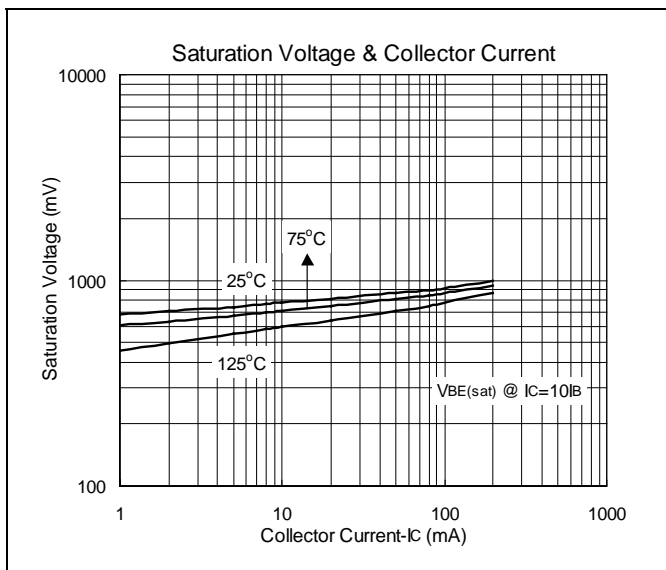
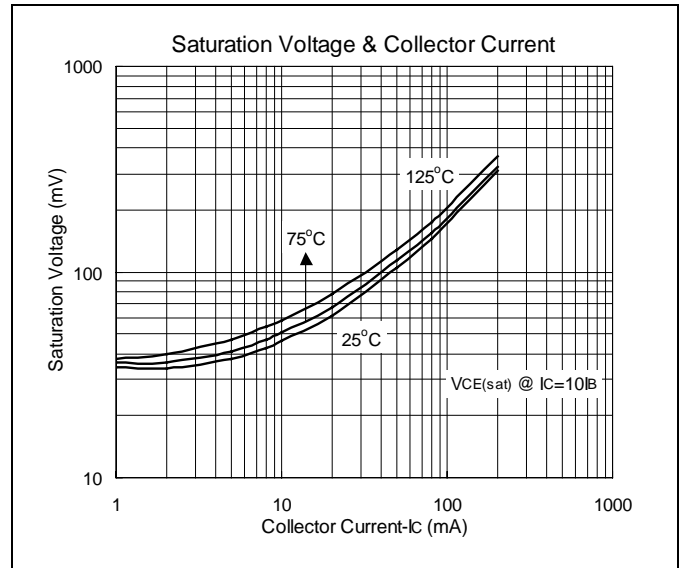
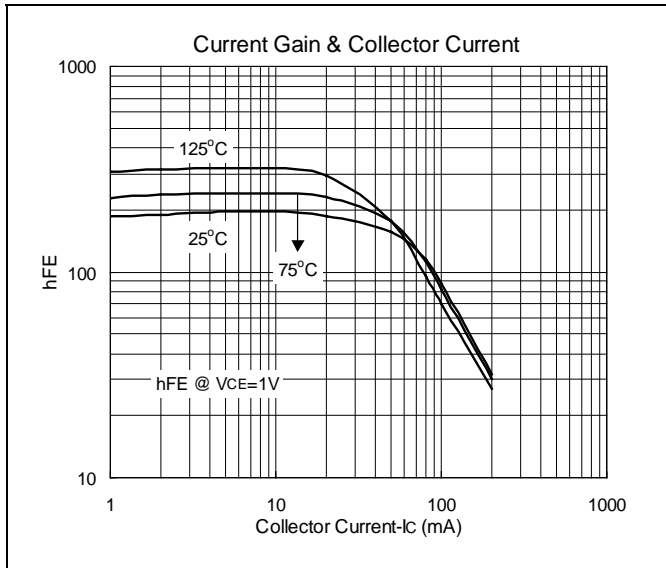
## Characteristics (Ta=25°C)

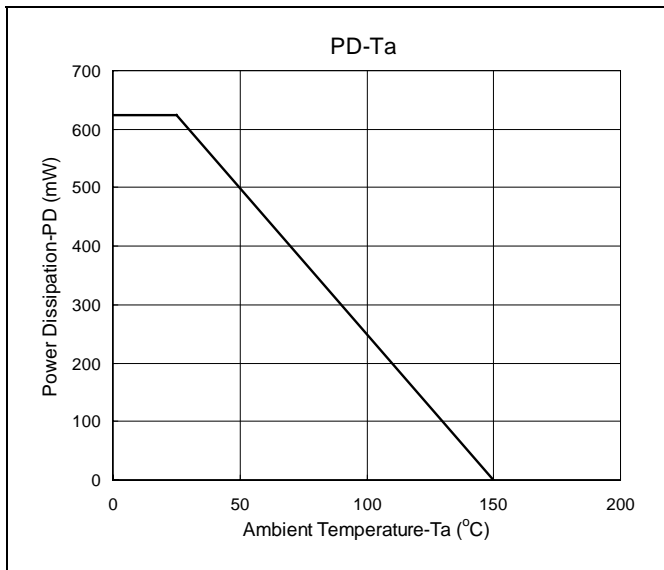
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA, IE=0
BVCEO	-40	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICEX	-	-	-50	nA	VCE=-30V, VBE=-3V
*VCE(sat)1	-	-	-250	mV	IB=-1mA, IC=-10mA
*VCE(sat)2	-	-	-400	mV	IB=-5mA, IC=-50mA
*VBE(sat)1	-650	-	-850	mV	IB=-1mA, IC=-10mA
*VBE(sat)2	-	-	-950	mV	IB=-5mA, IC=-50mA
*hFE1	60	-	-		VCE=-1V, IC=-100uA
*hFE2	80	-	-		VCE=-1V, IC=-1mA
*hFE3	100	-	300		VCE=-1V, IC=-10mA
*hFE4	60	-	-		VCE=-1V, IC=-50mA
*hFE5	30	-	-		VCE=-1V, IC=-100mA
fT	250	-	-	MHz	VCE=-20V, IC=-10mA,, f=100MHz
Cob	-	-	4	pF	VCB=-5V, IE=0, f=1MHz

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



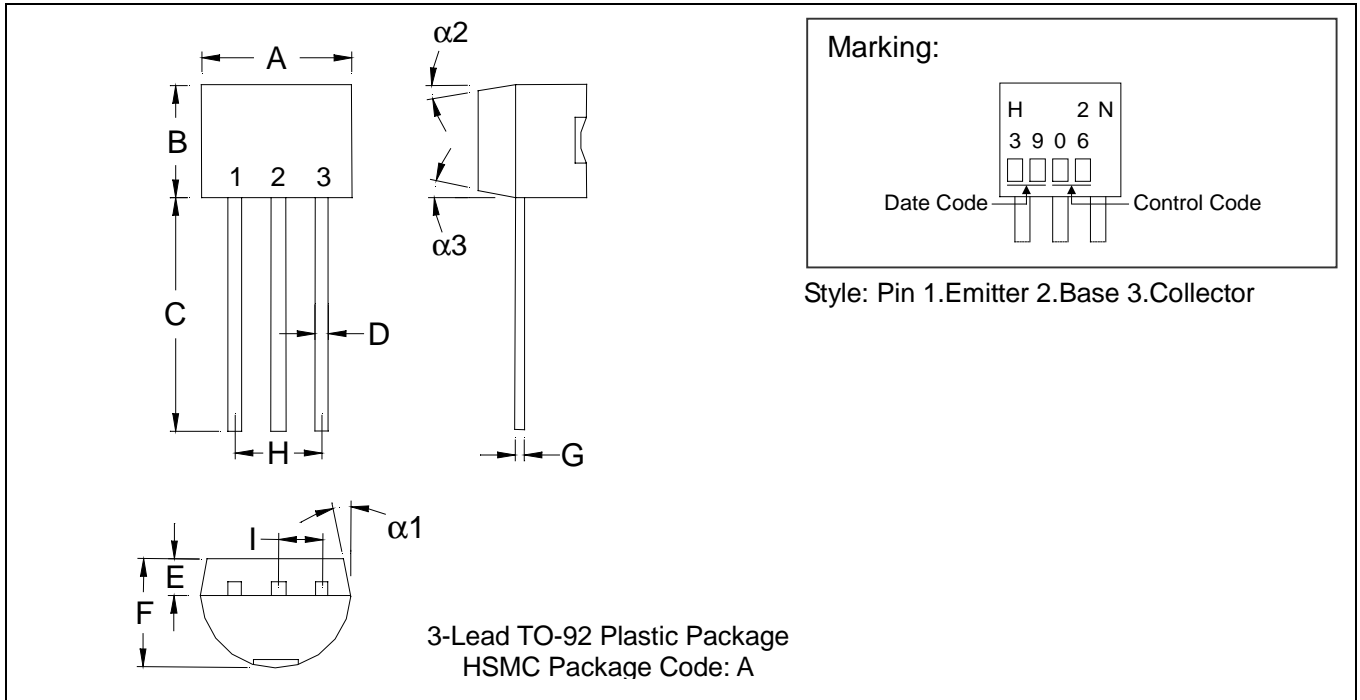
### Characteristics Curve







### TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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